

bq25050/bq25060EVM

This user's guide describes the features and operation of the bq25050/bq25060EVM Evaluation Module (EVM). This EVM assists users in evaluating the bq25050 and bq25060 linear battery chargers. The manual includes the bq25050/bq25060EVM bill of materials, board layout, and schematic.

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1 Introduction

1.1 EVM Features

- Evaluation module for bq25050/bq25060 (HPA577 E2)
- 30-V input rating, with 10.5-V overvoltage protection (OVP)
- FET controller for external battery FET for external power path control (BGATE)
- Programmable charge current
- Input voltage dynamic power management
- 50-mA integrated low-dropout (LDO) linear regulator
- Battery NTC monitoring during charge and discharge
- Thermal regulation and protection.
- Status indication – Charging/Done and Temperature Faults
- Jumpers available. Easy-to-change connections.

1.2 General Description

The bq25050/60 is a highly integrated Li-Ion linear battery charger targeted at space-limited portable applications. It operates from either a USB port or ac adapter and charges a single-cell Li-ion battery with up to 1 A of charge current. The 30-V input voltage range with input overvoltage protections supports low-cost unregulated adapters.

The bq25050/60 has a single power output that charges the battery. The system load is connected to OUT. The low-battery system startup circuitry maintains OUT greater than 3.4 V whenever an input source is connected. This allows the system to start up and run whenever an input source is connected regardless of the battery voltage. The charge current is programmable up to 1 A using the ISET input. Additionally, a 4.9-V, 50-mA LDO is integrated into the integrated circuit (IC) for supplying low power external circuitry.

The battery is charged in three phases: conditioning, constant current, and constant voltage. In all charge phases, an internal control loop monitors the IC junction temperature and reduces the charge current if an internal temperature threshold is exceeded. The charger power stage and charge current sense functions are fully integrated. The charger function has high accuracy current and voltage regulation loops, charge status display, and charge termination.

For details, see the bq25050 ([SLUSA33](#)) and bq25060 ([SLUSA32](#)) data sheets.

1.3 I/O Description

Table 1. I/O Description

Jack	Description
J1–Vin	USB or ac adapter positive output
J1–GND	USB or ac adapter negative output
J2–OUT	Connected to system load
J2–GND	Ground
J3–BAT	Connected to battery pack
J3–GND	Ground
J3–GND	Ground
J3–TS	Temperature qualification voltage input
J4–VLDO	LDO output
J4–GND	Ground
J5	1-wire interface
JP1–Hi	Charge-enable active-HIGH logic input.
JP1–Ctrl (EN)	IC reference voltage VREF
JP1–Lo	Ground

Table 1. I/O Description (continued)

Jack	Description
JP2-TS	Battery pack NTC monitoring input
JP2-TSADJ	Onboard TS potentiometer
JP3-OUT	Connected to J2-OUT
JP3-BAT	Connected to J3-BAT
JP4-Vin	Connected to J1-Vin
JP4-R5	Connected to R5
JP5-LED	LED cathode
JP5-CHG	Charge status indicator open-drain output
JP6-BGATE	Battery P-channel MOSFET gate drive output
JP6-GND	Ground

1.4 Control and Key Parameters Setting

Table 2. Control and Key Parameters Setting

Jack	Description	Factory Setting
JP1	Ctrl (EN) pin setting Connect Ctrl (EN) to Hi: Disables Chip Float Ctrl (EN) pin: USB100 mode or Ctrl from J5 (-001) Connect Ctrl (EN) to ground: ISET Ctrl	Float (No shunt) (-001) Low (JP1:2-3) (-002)
JP2	TS setting OFF: Connect TS to external battery pack NTC resistor ON: Connect TS to onboard potentiometer	Jumper ON
JP3	OUT and BAT setting OFF: Do not short OUT and BAT ON: Short OUT and BAT	Jumper OFF
JP4	Onboard bias supply setting	Jumper ON
JP5	CHG LED setting OFF: disconnect CHG and LED ON: CHG	Jumper ON
JP6	BGATE setting OFF: Enable BGATE ON: Disable BGATE	Jumper OFF

1.5 Recommended Operating Conditions

Table 3. Recommended Operating Conditions

Symbol	Description	Min	Typ	Max	Unit	Notes
Supply voltage, V_{IN}	Input voltage from ac adapter input	4.35	5	10.2	V	
Battery voltage, V_{BAT}	Voltage applied at VBAT terminal of J5			4.2	V	
Supply current, I_{AC}	Maximum input current from ac adapter input	0		1	A	
Charge current, I_{chg}	Battery charge current			1	A	
Operating junction temperature range, T_J		0		125	°C	

2 Equipment

2.1 Power Supplies

Power Supply 1 (PS#1): Adjustable from 0 to ≥ 5.1 Vdc at ≥ 1.5 A, use for input J1.

Power Supply 2 (PS#2): Adjustable from 0 to ≥ 5.1 Vdc at ≥ 2.5 A, used for Battery Load board.

2.2 Loads

Load #1: $25 \Omega \pm 5\%$, ≥ 5 W.

Load #2: PR1010: Battery Load Circuit board, as shown in [Figure 4](#).

LDO load: 1-k Ω resistor, 200 mW

2.3 Meters

Five Fluke 75 DMMs (equivalent or better).

2.4 Computer and Interface

A computer with at least one USB port.

HPA172, for -001 only.

3 Equipment Setup

The original test setup of HPA577-001 is shown in [Figure 1](#).

The original test setup of HPA577-002 is shown in [Figure 2](#).

1. Set the power supply #1 for 5.1 V \pm 100 mVdc, 1.5 \pm 0.1-A current limit and then turn off supply.
2. Connect the output of power supply #1 in series with a current meter (multimeter) to J1 (VIN, GND).
3. Connect a voltage meter across J1 (VIN, GND).
4. Apply a 1-k Ω load resistor across J4 (VLDO, GND).
5. Connect Load #1 to J2 (OUT, GND).
6. Connect the Battery Load Circuit board to J3 (BAT, GND).
7. Set PS#2 to 2.3 Vdc \pm 100 mV and 2.5-A current limit, turn off and connect to the Battery Load Circuit board.
8. Connect a voltage meter across J2 (OUT, GND).
9. Connect a voltage meter across J3 (BAT, GND).
10. Verify the shunts are placed correctly as per [Table 2](#).
11. For HPA577-001 (bq25050 EVM) only:

Connect J5 to a computer with a USB Interface Adapter (HPA172).

The USB Interface Adapter software is available in the product folder at www.ti.com by searching for the part number bq25050 and selecting the bq25050EVM link. A zip file under the Software and Tools section can be downloaded. Extract the files onto the local hard drive, and double-click on the bq25050.exe application evaluation file. A screen shot is shown in [Figure 1](#).

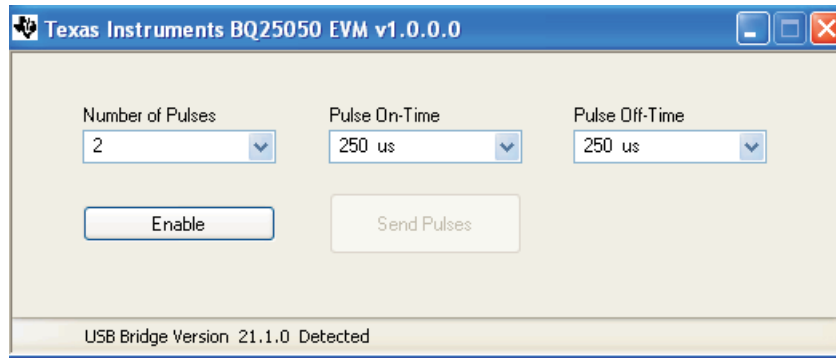
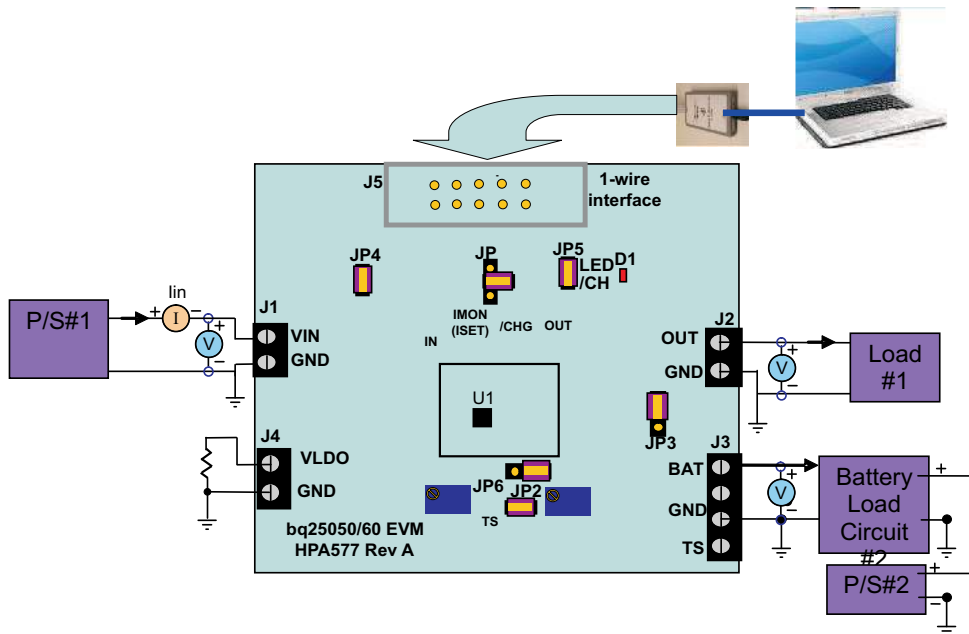


Figure 1. Original Test Setup for HPA577-001 – bq25050EVM

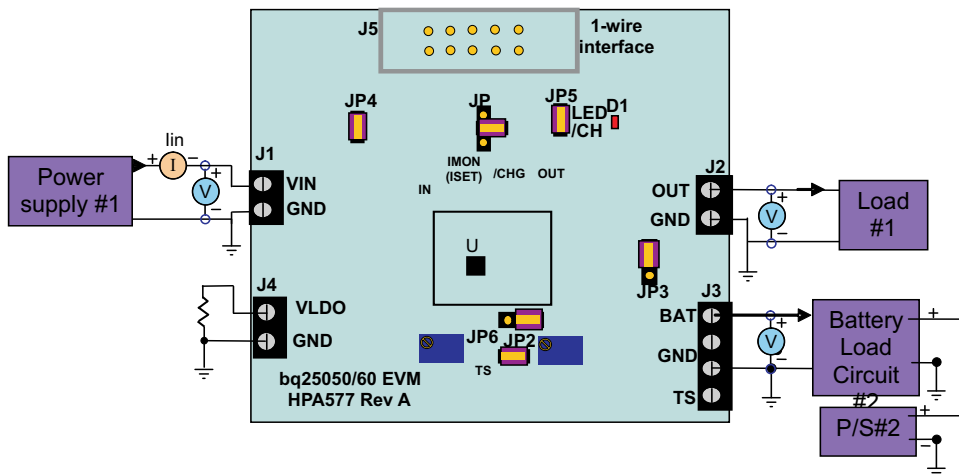


Figure 2. Original Test Setup for HPA577-002 – bq25060 EVM

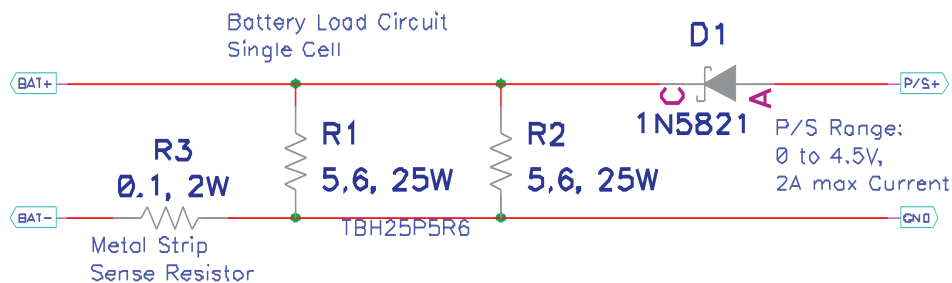


Figure 3. Battery Load Circuit – Replacement for a Single Cell Li-Ion Battery → BAT+ to BAT– Voltage Tracks P/S Input Voltage Minus 1 Diode Drop.

4 Procedure

4.1 Charger Operation with Minimum System Voltage Mode

4.1.1 Turn on PS#1, preset to 5.1 Vdc

Measure → $V(J4(VLDO)) = 4.9 \pm 100 \text{ mV}$

4.1.2 For -001: Trim R7, and set TS pin voltage to $0.5 \text{ V} \pm 50 \text{ mV}$. In the software window, click on enable.

For -002: Trim R7 and set TS pin voltage to $1 \text{ V} \pm 50 \text{ mV}$.

For -001 and -002: Turn on PS#2 set to $2.3 \text{ V} \pm 50 \text{ mV}$.

Observe → D1(/CHG) on – This is precharge mode and OUT is held at its minimum system voltage while the adapter is present and the battery below this minimum voltage. This allows system power-up with a discharged battery.

Measure → $I_{in} = 180 \text{ mA} \pm 30 \text{ mA}$

Measure → $V(J2(OUT)) = 3.5 \text{ V} \pm 200 \text{ mV}$

4.1.3 Increase PS#2 to ~3.3 Vdc to raise VBAT to $3 \text{ V} \pm 50 \text{ mV}$

Observe → D1(/CHG) on – This is fast-charge constant current mode and OUT is held at its minimum system voltage while the adapter is present and the battery below this minimum voltage. This allows system power-up with a discharged battery.

For -001 Measure → $I_{in} = 285 \text{ mA} \pm 50 \text{ mA}$

For -002 Measure → $I_{in} = 467 \text{ mA} \pm 50 \text{ mA}$

Measure → $V(J2(OUT)) = 3.5 \text{ V} \pm 200 \text{ mV}$.

4.1.4 Increase PS#2 to ~4.1Vdc to raise VBAT to $3.8 \text{ V} \pm 50 \text{ mV}$.

Observe → D1(/CHG) on – This is fast-charge constant current mode and the battery is above the minimum OUT voltage (with adapter present) so that the external BAT FET is enabled, and Vout and Vbat track.

For -001 Measure → $I_{in} = 285 \text{ mA} \pm 50 \text{ mA}$

For -002 Measure → $I_{in} = 467 \text{ mA} \pm 50 \text{ mA}$

Measure → $V(J2(OUT)) = 3.8 \text{ V} \pm 200 \text{ mV}$

4.1.5 Increase PS#2 until D1 turns off indicating charger termination, to ~4.5 Vdc to raise VBAT to ~4.22 V.

Observe → D1(/CHG) off – Once terminated, the adapter powers the system. If the BAT pin is driven too high in voltage by P/S#2, the battery overvoltage protection kicks in and turns off the input FET, and the battery powers the system. This condition does not normally occur with a battery in place of the battery bias circuit.

Measure → $I_{in} = 180 \text{ mA} \pm 50 \text{ mA}$

Measure → $V(J2(OUT)) = 4.2 \text{ V} \pm 200 \text{ mV}$

4.1.6 Decrease PS#2 to ~4.1 Vdc to lower VBAT to 3.8 V ± 50 mV.

Observe → D1(/CHG) on – this shows refresh of the cell once some of the charge is removed.

For -001 Measure → $I_{in} = 285 \text{ mA} \pm 50 \text{ mA}$

For -002 Measure → $I_{in} = 467 \text{ mA} \pm 50 \text{ mA}$

Measure → $V(J2(OUT)) = 3.8 \text{ V} \pm 200 \text{ mV}$

4.2 Input Current Setting

4.2.1 For HPA577-001 (bq25050 EVM) only:

In the software interface window, select 7 on "Number of Pulses," and click on "Send Pulses" to bq25050EVM.

Measure → $I_{in} = 374 \text{ mA} \pm 50 \text{ mA}$

4.2.2 For HPA577-002 (bq25060 EVM) only:

PUT JP1 between EN and LO; trim R6 and observe the input current change.

Set → $I_{in} = 374 \text{ mA} \pm 50 \text{ mA}$

4.3 Charger Cut-Off by Thermistor

4.3.1 For HPA577-001 (bq25050 EVM) only:

Slowly trim R7 until $V(J3(TS)) = 0.675 \text{ V} \pm 50 \text{ mV}$.

Observe → D1 (/CHG) flashing. This indicates a temperature fault that was tripped by the cold temperature threshold comparator.

Trim R7 CW until $V(J3(TS)) = 0.5 \text{ V} \pm 50 \text{ mV}$.

Observe → D1 (/CHG) on.

Trim R7 CW until $V(J3(TS)) = 0.75 \text{ V} \pm 50 \text{ V}$.

Observe → D1 (/CHG) flashing. This indicates a temperature fault which was tripped by the hot temperature threshold comparator.

Trim R2 CCW until $V(J3(TS)) = 0.5 \text{ V} \pm 50 \text{ mV}$.

Observe → D1 (/CHG) on.

4.3.2 For HPA577-002 (bq25060 EVM) only:

Slowly trim R7 until $V(J3(TS)) = 1.30 \text{ V} \pm 50 \text{ mV}$

Observe → D1 (/CHG) off. This indicates a temperature fault that was tripped by the cold temperature threshold comparator

Trim R7 until $V(J3(TS)) = 1 \text{ V} \pm 50 \text{ mV}$.

Observe → D1 (/CHG) on.

Continue to trim R7 CW until $V(J3(TS)) = 0.550 \text{ V} \pm 50 \text{ mV}$

Observe → D1 (/CHG) off. This indicates a temperature fault that was tripped by the hot temperature threshold comparator.

Trim R7 CCW until $V(J3(TS)) = 1 \text{ V} \pm 50 \text{ mV}$.

Observe → D1 (/CHG) on.

5 PCB Layout Guideline

It is important to pay special attention to the printed-circuit board (PCB) layout. The following provides some guidelines:

1. To obtain optimal performance, the decoupling capacitor from IN to GND (thermal pad) and the output filter capacitors from OUT to GND (thermal pad) must be placed as close as possible to the bq25050/60, with short trace runs to both IN, OUT, and GND (thermal pad).
2. All low-current GND connections must be kept separate from the high-current charge or discharge paths from the battery. Use a single-point ground technique incorporating both the small signal ground path and the power ground path.
3. The high current charge paths into IN pin and from the OUT pin must be sized appropriately for the maximum charge current in order to avoid voltage drops in these traces.
4. The bq25050/60 is packaged in a thermally enhanced SON package. The package includes a thermal pad to provide an effective thermal contact between the IC and the PCB; this thermal pad is also the main ground connection for the device. Connect the thermal pad to the PCB ground connection. Full PCB design guidelines for this package are provided in the application report entitled: *QFN/SON PCB Attachment Application Note* ([SLUA271](#)).

6 Bill of Materials, Board Layout, and Schematics

6.1 Bill of Materials

Table 4. Bill of Materials

Count		RefDes	Value	Description	Size	Part Number	MFR
-001	-002						
2	2	C1, C5	0.1uF	Capacitor, Ceramic, 0.1-uF, 25-V, X7R, 10%	1206	Std	Std
1	1	C2	1uF	Capacitor, Ceramic, 1uF, 25-V, X7R, 10%	1206	Std	Std
1	1	C3	1uF	Capacitor, Ceramic, 1-uF, 6.3V, X5R, 20%	0805	Std	Std
1	1	C4	22uF	Capacitor, Ceramic, 22uF, 10V, X5R, 20%	1206	ECJ-HVB1A226M	Panasonic
2	2	C6, C7	0.1uF	Capacitor, Ceramic, 0.1uF, 25V, X7R, 10%	0603	Std	Std
0	0	C8	DNP	Capacitor, Ceramic, Low Inductance, vvV, [temp], [tol]	0603	Std	Std
1	1	D1	Red	Diode, LED, Red, 1.8-V, 20-mA, 20-mcd	0603	LTST-C190CKT	Liteon
1	1	D2	BZX84C6v2T	Diode, Zener, 6.2-V, 350-mW	SOT-23	BZX84C6V2-7-F	Diodes
3	3	J1, J2, J4	ED1514	Terminal Block, 2-pin, 6-A, 3.5mm	0.27 x 0.25	ED555/2DS	OST
1	1	J3	ED555/4DS	Terminal Block, 4-pin, 6-A, 3.5mm	0.55 x 0.25 inch	ED555/4DS	OST
1	0	J5		Connector, Male Straight 2x5 pin, 100mil spacing, 4 Wall	0.338 x 0.788 inch	N2510-6002-UB	3M
1	1	JP1	PEC03SAAN	Header, Male 3-pin, 100mil spacing,	0.100 inch x 3	PEC03SAAN	Sullins
5	5	JP2, JP3, JP4, JP5, JP6	PEC02SAAN	Header, Male 2-pin, 100mil spacing,	0.100 inch x 2	PEC02SAAN	Sullins
1	1	Q1	NTR4101P	Trans, PChan FET -20V, 3.2A, Rds 0.070 Ohm	SOT-23	NTR4101PT1G	OnSemi
0	1	R1	24.3k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
0	1	R2	11.3k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
2	2	R3, R5	1k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	1	R4	1.5k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	1	R6	10k	Potentiometer, 1/4 in. Cermet, 12-Turn, Top-Adjust	0.25x0.17 inch	3266W-103LF	Bourns
1	1	R7	200k	Potentiometer, 1/4 Cermet, 12-Turn, Top-Adjust	0.25x0.17 inch	3266W-204LF	Bourns
1	0	R8	0	Resistor, Chip, 1/16W, 5%	0603	Std	Std
1	0	U1	BQ25050DQC	IC, 1A, Single-Input, Single Cell Li-Ion BATTERY CHARGER with 50mA LDO and Minimum System Voltage Support	TDFN-10	BQ25050DQC	TI
0	1	U1	BQ25060DQC	IC, 1A, Single-Input, Single Cell Li-Ion BATTERY CHARGER with 50mA LDO and Minimum System Voltage Support	TDFN-10	BQ25060DQC	TI
1	1	—		PCB, 2 In x 1.875 In x 0.031 In		HPA577	Any
6	6	—		Shunt, 100-mil, Black	0.100	929950-00	3M

6.2 Board Layout

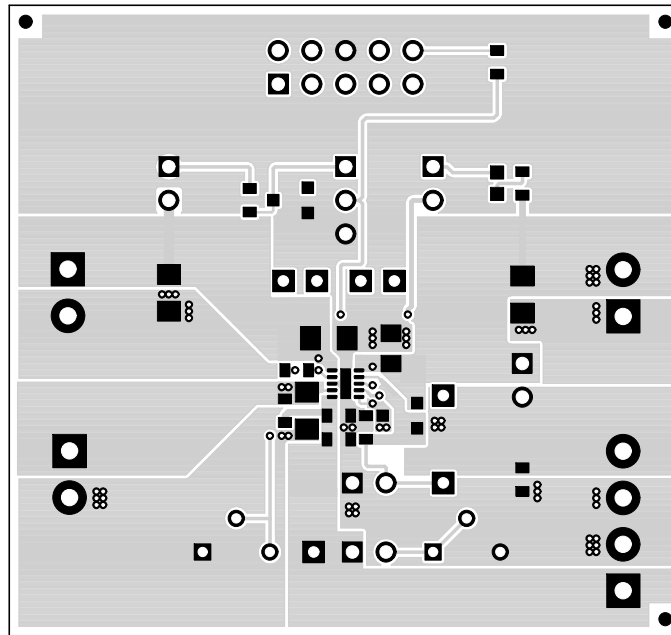


Figure 4. Top Layer

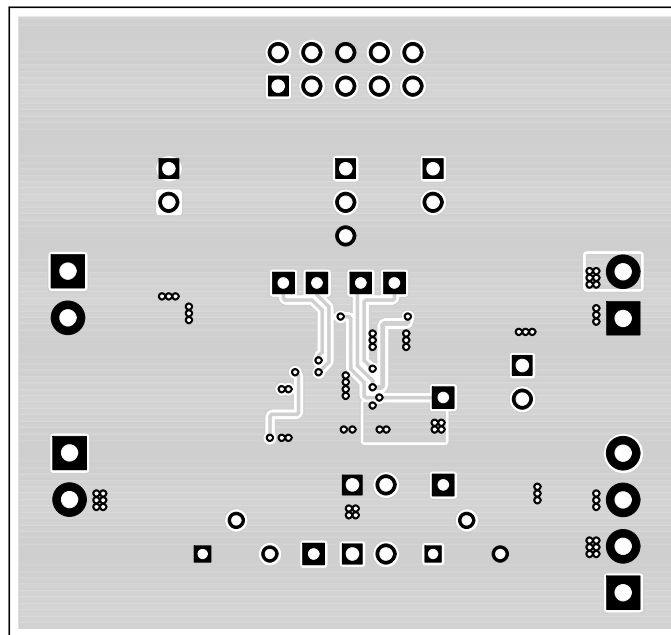


Figure 5. Bottom Layer

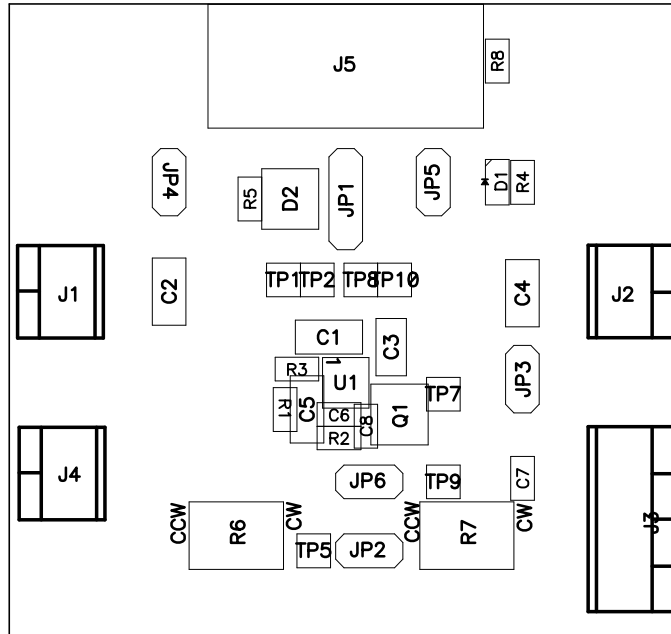


Figure 6. Top Assembly

6.3 Schematic

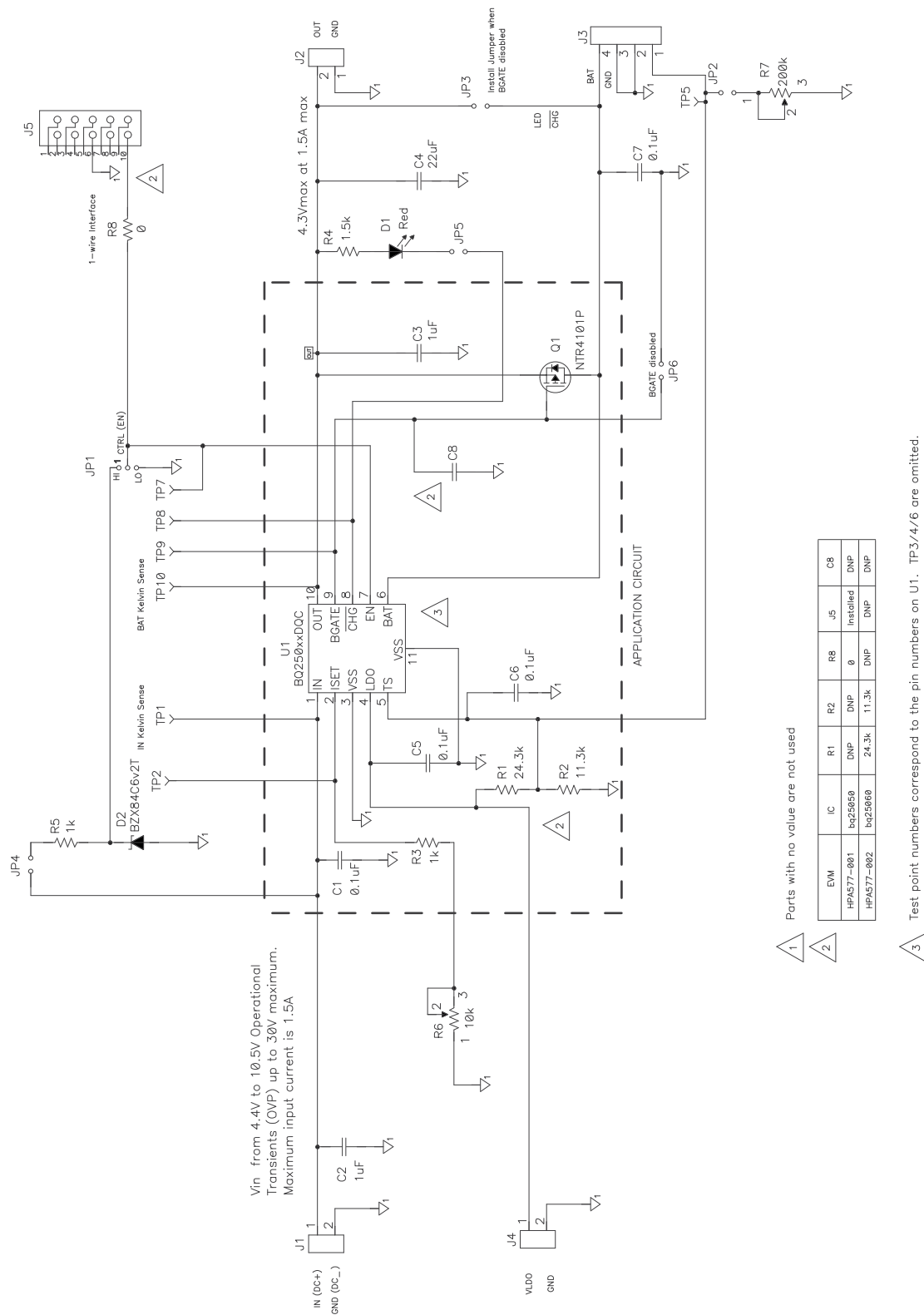


Figure 7. bq25050/60 EVM Schematic (Sheet 1 of 1)

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EVM Warnings and Restrictions

It is important to operate this EVM within the input voltage range of 4.35 V to 10 V and the output voltage range of 0 V to 4.3 V .

Exceeding the specified input range may cause unexpected operation and/or irreversible damage to the EVM. If there are questions concerning the input range, please contact a TI field representative prior to connecting the input power.

Applying loads outside of the specified output range may result in unintended operation and/or possible permanent damage to the EVM. Please consult the EVM User's Guide prior to connecting any load to the EVM output. If there is uncertainty as to the load specification, please contact a TI field representative.

During normal operation, some circuit components may have case temperatures greater than 60°C. The EVM is designed to operate properly with certain components above 125°C as long as the input and output ranges are maintained. These components include but are not limited to linear regulators, switching transistors, pass transistors, and current sense resistors. These types of devices can be identified using the EVM schematic located in the EVM User's Guide. When placing measurement probes near these devices during operation, please be aware that these devices may be very warm to the touch.

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